

## **ABSTRACT OF THE DISCLOSURE**

A method for preparing thin integrated circuits having multiple circuit layers has the following acts of: forming a first circuit layer on a substrate; depositing at least one resin and copper layer on the first circuit layer; forming a second circuit layer on the at least one resin and copper layer; electrically connecting the first and second circuit layers; attaching electronic components to the first or second circuit layers; applying an encapsulant layer to protect the electronic components; and removing the substrate to expose the first circuit layer. By removing the substrate, the integrated circuit is much thinner.